

Student Software Competition

Student Software Competition · Packaging Benchmark Award · Student Travel Grant

EDAPS 2026 Student Software Competition

Call for Participation

The EDAPS 2026 Student Software Competition invites students to develop and showcase innovative software solutions for electrical design, analysis, and optimization of electronic packages and systems.

Submissions should present original, software-driven contributions in areas such as design, automation, co-optimization, analysis, or regression — with clear emphasis on novelty, technical rigor, and practical impact.

Submission Requirements

- **Functional software prototype** — To be demonstrated live at the conference (in-person)
- **Technical report** — 1 page IEEE-format report describing methodology, implementation, and results

Eligibility

- The primary contributor must be a **student (UG / Masters / PhD)**. Teams are allowed, with a clearly identified student lead.

Special Incentive

Additional grants will be awarded to teams demonstrating their solutions using the EDMS EPS Packaging Benchmark database. See the Packaging Benchmark Award section below for full details.

Scope

Relevant topics include, but are not limited to:

- Electrical modelling of packages, interconnects, and systems
- Signal integrity (SI), power integrity (PI), and EMI/EMC analysis
- Design automation and optimization workflows
- Co-optimization across domains
- AI/ML, surrogate modelling, or regression techniques
- Fast solvers, model order reduction, and numerical methods
- Benchmark-driven validation and reproducibility

Submission Guidelines

Submission deadline: ~~Sept 1'2026~~ Sept 21'2026

Notification of acceptance: Oct 8'2026

- Software must be functional, demonstrable, and central to the contribution
- Work must show clear novelty beyond existing approaches
- Use of external libraries or datasets must be properly credited and disclosed
- At least one team member must register for EDAPS 2026
- Teams should be prepared for technical Q&A during evaluation
- Please send your entries as attachment to admin@edaps.com with the subject "EDAPS 2026: Student Software Competition Entry"

Evaluation Criteria

Criterion	Weight
Innovation & Novelty	25%
Technical Depth of the Algorithm	25%
Demonstration	15%
Validation & Results	25%
Impact & Relevance	10%

Awards

- Best Student Software Award – 500\$
- Benchmark Excellence Award (EDMS EPS database usage)

Additional grants may be awarded for benchmarking integration and reproducibility.

Notes

- Selected teams must present in person at EDAPS 2026
- Submissions must be original and not previously commercialized

IEEE EPS TC-EDMS Packaging Benchmark Award

The IEEE EPS Society's Technical Committee on Electrical Design, Modeling and Simulation (TC-EDMS) maintains a joint industrial-academic effort to establish a modern, publicly available Packaging Benchmark Suite for verification, validation, and performance benchmarking. The benchmark cases cover electromagnetic, electrical, and circuit modeling/simulation problems, along with state-of-the-art solution methods used in designing, analyzing, and developing electronic packages.

For more information, visit packaging-benchmarks.org.

Award Categories

1. Utilization of Packaging-Benchmark Cases

- **Abstract submission** documenting the effort in utilization of Packaging-Benchmarks — selected submissions eligible up to \$1,000. The TC-EDMS committee evaluates submissions at the beginning of every month; committee decision is final.
- **Accepted paper** at EPS conferences (EPEPS, EDAPS, SPI, DTMES) using Packaging-Benchmark cases — selected submission eligible for an additional \$1,000; selection decided by the conference TPC.
- **Best paper award** received at EPS conferences using Packaging-Benchmark cases — eligible for an additional \$1,000.
- **Eligible candidates:** Masters and PhD students, Postdoctoral Researchers, Early-stage Professionals.

2. Submission of Packaging-Benchmark Cases

- **Abstract submission** documenting the proposed benchmark and the timeline to completion — selected submissions eligible up to \$1,000.
- **Complete submission** to the Packaging-Benchmark website — selected submissions eligible for an additional \$2,000.
- **Eligible candidates:** students, researchers, and industry professionals.

All Applications Should Be Sent To

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